

IN THE ABSTRACT:

Please amend the abstract as follows. A marked-up copy of the abstract, showing the changes made thereto, is attached in Appendix A.

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g1 -- An exposure method and an exposure apparatus in which one or more plural sample shot processes are made to a substrate and an exposure process is made to the substrate after completion of the sample shot process or processes. The procedure includes a first determining step for determining the processing order in a first sample shot process, of the plural sample shot processes, and a second determining step for determining the processing order in a second sample shot process to be made after the first sample shot process. In at least one of the first and second determining steps, the determination is made under a condition that an interval between a shot to be processed last in the first sample shot process and a shot to be processed first in the second sample shot process is shortened. --

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IN THE SPECIFICATION:

Please amend the specification as follows:

Please substitute the paragraph beginning at page 1, line 9, with the following. A marked-up copy of this paragraph, showing the changes made thereto, is attached in Appendix A.

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22 -- The wafer processing procedure for producing "exposed wafers" mainly comprises sample shot processes such as global tilting for removing any tilt of a wafer and global alignment for positioning the wafer, as well as an exposure process. Many attempts have been made to

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